

**Q1** 

**1U Passive Heat Sink** 

**PRODUCT SPECIFICATIONS** 



## Model Number: Q1

- Recommend for Intel® CPU as following
  - Intel<sup>®</sup> Alder Lake S Processor, Socket LGA 1700
- Passive Heat Sink for 1U Server

## **Overall Specification**

Dimension	90 x 90 x 27 mm
Weight	534g ±5g
Material	Copper Heat Sink with Skiving Fins
Mounting	Captive Mounting Design
Back Strip	Included
Thermal Grease	Pre-Printed with SHIN-ETSU 7762
TDP	Support 125 Watts CPU Power Heat Dissipation

## Performance Chart: Q1 Thermal Resistance

## Thermal Performance vs. Airflow





